AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions of claims in the application.

1. (Withdrawn): A method for protecting a semiconductor device, comprising the step of:

attaching a protection member detachably to the semiconductor device that includes one or more elements.

2. (Withdrawn): A method for protecting a semiconductor device that is subjected to a plurality of treatments after fabrication but before shipment, comprising the step of:

performing the treatments with a protection member being attached to the semiconductor device.

3. (Withdrawn): The method as claimed in claim 2, wherein

the treatments include transportation of the semiconductor device with the semiconductor device being held by a suction chuck through a suction hole formed on the protection member.

4. (Withdrawn): A method for testing a semiconductor device, comprising the step of:

attaching a semiconductor device protection cover detachably to the semiconductor device; and

pressing the semiconductor device against an IC contactor with the semiconductor device protection cover therebetween for a test.

5. (Currently amended): A semiconductor device protection cover attached to a semiconductor device, comprising:

a base portion;

a first surface, said first surface being flat;

a second surface having a projecting portion to be brought into contact with a substrate of the semiconductor device and a depressed portion not to be brought into contact with parts mounted in the semiconductor device, wherein the substrate has a semiconductor chip mounted thereon, wherein the substrate has a semiconductor chip mounted thereon; and

an engaging portion to engage the semiconductor device protection cover with the substrate of the semiconductor device, so as to detachably attach the semiconductor device protection cover to the semiconductor device.

6. (Cancelled).

7. (Original): The semiconductor device protection cover as claimed in claim 5, wherein the projecting portion and the base portion of the semiconductor device protection cover are formed from materials having hardness higher than a surface of the semiconductor device.

8. (Original): The semiconductor device protection cover as claimed in claim 5, wherein the projecting portion and the base portion of the semiconductor device protection cover are formed from materials having hardness lower than a surface of the semiconductor device.

9. (Original): The semiconductor device protection cover as claimed in claim 5, wherein the projecting portion and the base portion of the semiconductor device protection cover are formed from elastic materials.

10. (Original): The semiconductor device protection cover as claimed in claim 5, wherein

the projecting portion and the base portion of the semiconductor device protection cover have conductivity.

11. (Cancelled).

12. (Previously presented): The semiconductor device protection cover as claimed in claim 5, wherein the base portion has a predetermined shape irrespective of an outer shape of the semiconductor device.

13. (Currently amended): A semiconductor device protection cover attached to a semiconductor device, comprising:

a base portion;

a first surface, said first surface being flat; and

a second surface to be brought into contact with a substrate of the semiconductor device and with parts mounted in the semiconductor device, said second surface being formed from an elastic material, wherein the substrate has a semiconductor chip mounted thereon,

wherein the semiconductor device protection cover has a structure to engage with the semiconductor device so as to be detachably attached to the semiconductor device.

14. (Currently amended): A semiconductor device unit, comprising:

a semiconductor device; and

a semiconductor device protection cover,

wherein the semiconductor device protection cover comprises:

a base portion;

a first surface, said first surface being flat; and

a second surface having a projecting portion to be brought into contact with a substrate of the semiconductor device and a depressed portion not to be brought into contact with parts mounted in the semiconductor device, wherein the substrate has a semiconductor chip mounted thereon,

wherein the semiconductor device protection cover has a structure to engage with the semiconductor device so as to be detachably attached to the semiconductor device.

15. (Original): The semiconductor device unit as claimed in claim 14, wherein

the semiconductor device has a first positioning member; and

the semiconductor device protection cover has a second positioning member, the semiconductor device and the semiconductor device protection cover being set in position when the first positioning member and the second positioning member are engaged with each other.

16. (Original): The semiconductor device unit as claimed in claim 15, wherein

the first positioning member is a projection; and

the second positioning member is a recess engagable with the projection.

17. (Original): The semiconductor device unit as claimed in claim 16, wherein an inclined surface is formed on the projection for guiding insertion of the projection into the recess.

18. (Original): The semiconductor device unit as claimed in claim 15, wherein

the first positioning member is a peripheral part of the semiconductor device; and

the second positioning member is a wall engagable with the peripheral part.

19. (Original): The semiconductor device unit as claimed in claim 18, wherein

an inclined surface is formed on the second positioning member for guiding the first positioning member to engage with the second positioning member.

20. (Original): The semiconductor device unit as claimed in claim 15, wherein

the first positioning member and the second positioning member are formed by recognition marks.

21. (Withdrawn): A semiconductor device packaging structure for packaging a semiconductor device, comprising:

a tray including a first semi-tray and a second semi-tray, the semiconductor device being attached to and packaged in the tray; and

a semiconductor device protection cover arranged between the first semi-tray and a surface of the semiconductor device,

wherein

the semiconductor device protection cover comprises:

a base portion;

a first surface, said first surface being flat; and

a second surface having a projecting portion to be brought into contact with a substrate of the semiconductor device and a depressed portion not to be brought into contact with parts mounted in the semiconductor device.

22. (Withdrawn): A semiconductor device package structure for packaging a semiconductor device, comprising:

an embossed tape on which the semiconductor device is pasted; and

a semiconductor device protection cover arranged on a surface of the semiconductor device,

wherein

the semiconductor device protection cover comprises:

a base portion;

a first surface, said first surface being flat; and

a second surface having a projecting portion to be brought into contact with a substrate of the semiconductor device and a depressed portion not to be brought into contact with parts mounted in the semiconductor device.

23. (Previously presented): The semiconductor device protection cover as claimed in claim 5, wherein the second surface having a plurality of bump recesses to accommodate solder balls, said bump recesses positioned corresponding to solder balls arranged on the semiconductor device.

24. (Previously presented): The semiconductor device protection cover as claimed in claim 5, wherein the depressed portion forming an opening penetrating through the base portion.

25. (Previously presented): The semiconductor device protection cover as claimed in claim 5, wherein the depressed portion forming a plurality of openings penetrating through the base portion and a plurality of ribs between the openings.